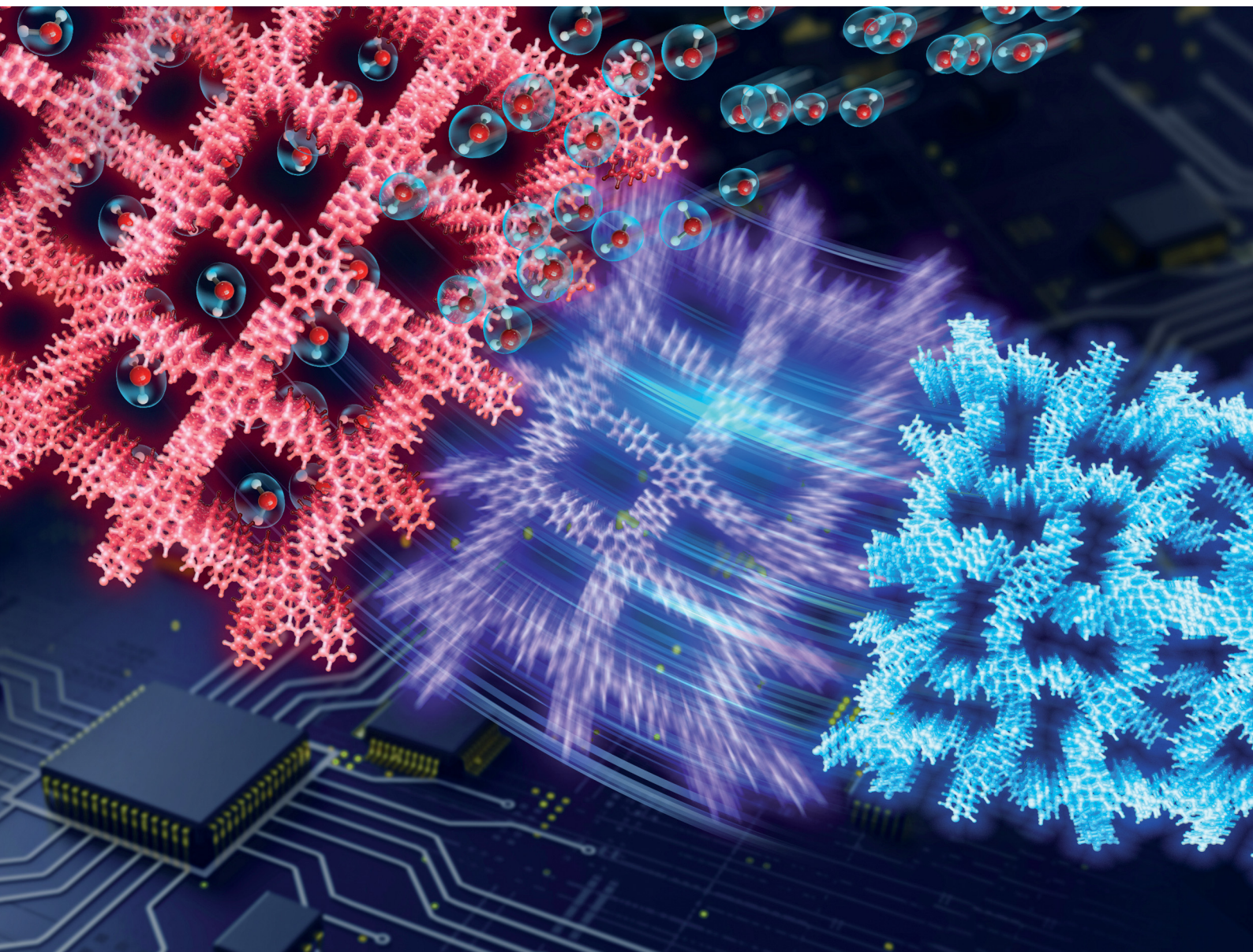


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## COMMUNICATION



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# Reversible and high-contrast thermal conductivity switching in a flexible covalent organic framework possessing negative Poisson's ratio†

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The ability to dynamically and reversibly control thermal transport in solid-state systems can redefine and propel a plethora of technologies including thermal switches, diodes, and rectifiers. Current material systems, however, do not possess the swift and large changes in thermal conductivity required for such practical applications. For instance, stimuli responsive materials, that can reversibly switch between a high thermal conductivity state and a low thermal conductivity state, are mostly limited to thermal switching ratios in the range of 1.5 to 4. Here, we demonstrate reversible thermal conductivity switching with an unprecedented 18× change in thermal transport in a highly flexible covalent organic framework with revolving imine bonds. The pedal motion of the imine bonds is capable of reversible transformations of the framework from an expanded (low thermal conductivity) to a contracted (high thermal conductivity) phase, which can be triggered through external stimuli such as exposure to guest adsorption and desorption or mechanical strain. We also show that the dynamic imine linkages endow the material with a negative Poisson's ratio, thus marking a regime of materials design that combines low densities with exceptional thermal and mechanical properties.

Actively manipulating the thermal conductivity of materials can not only enable novel directions of research in fundamental science but can also have transformative impacts on various technologies through proper engineering of new thermal diodes, regulators and switches.<sup>1</sup> For example, materials with dynamic and high thermal conductivity switching ratios can transform the field of nanophononics,<sup>2,3</sup> revolutionize thermal management strategies for microelectronics,<sup>4,5</sup> lead to the

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† Electronic supplementary information (ESI) available: References for Fig. 1 and Fig. 4b, details of the equilibrium molecular dynamics (EMD) and nonequilibrium molecular dynamics (NEMD) simulations, calculations of radial distribution functions, X-ray diffraction patterns, stress-strain calculations on COF-300, vibrational density of states calculations, and videos of pore expansion and contraction facilitating the low and high thermal conductivity states, respectively. See DOI: <https://doi.org/10.1039/d3mh01417g>

## New concepts

Reversible control of thermal conductivity in stimuli responsive materials is not only of importance from a fundamental materials science perspective but holds great promise for a plethora of applications. However, materials with fast and high-contrast thermal switching ratios for practical applications have been few and far between, thus limiting the advancements in such technologies. We demonstrate an unprecedented 18× change in thermal conductivity in a highly flexible covalent organic framework endowed with swift and reversible thermal transport control that exceeds the thermal switching ratios reported thus far in any material system. Through systematic atomistic simulations, we show that the key mechanism dictating such large changes in the intrinsic thermal transport properties is the dynamic pedal motion of the imine bonds that allows for the reversible transitions of the flexible covalent organic framework from expanded, low thermal conductivity to contracted, high thermal conductivity states. Furthermore, we also show that these lightweight materials are endowed with highly flexible frameworks and a negative Poisson's ratio, thus combining a host of superlative physical properties in one material system.

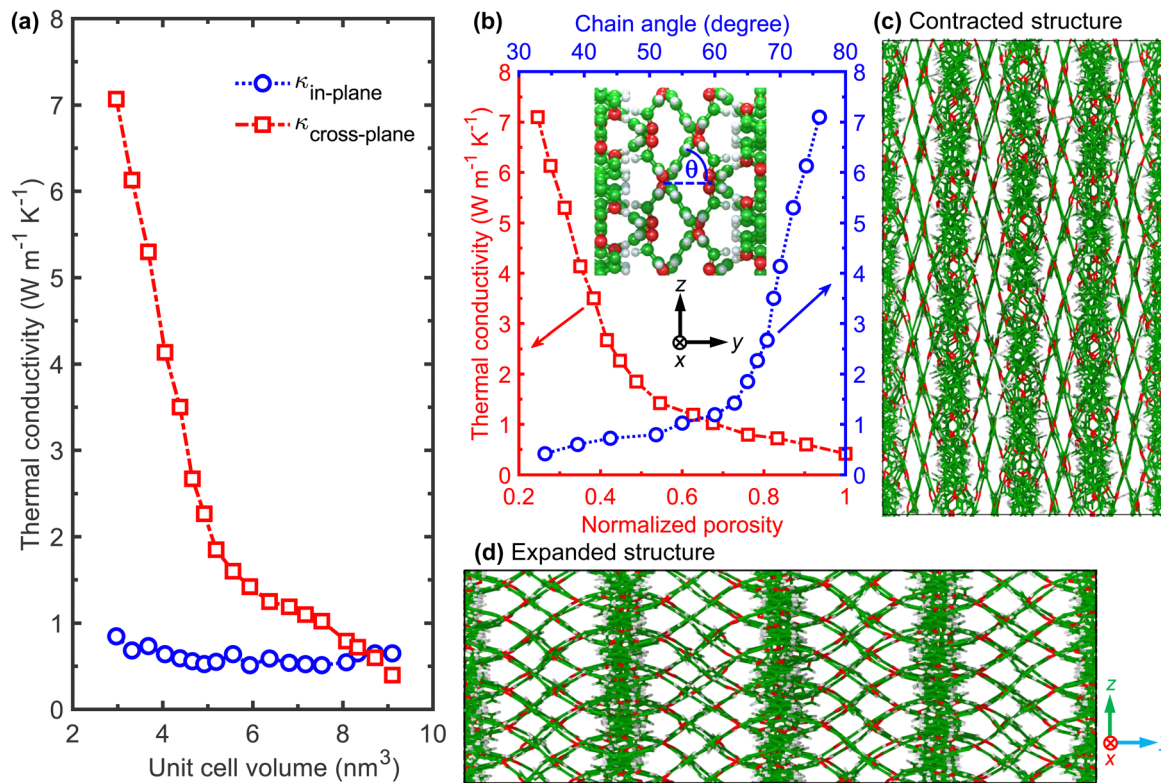
emergence of thermally driven logic gates and transistors,<sup>1,2</sup> and provide advancements in all solid-state electrocaloric refrigeration.<sup>6</sup> Although the efficiencies of such devices cannot rival their well-established electrical analogs that modulate current flow, the prospect of utilizing wasted heat as the source to 'power' such thermally driven devices is very appealing with far-reaching consequences, such as that of combating the issue of the ever-depleting nonrenewable energy resources. Yet, the advancements in such technologies are critically hinged upon designing materials with reversible and high-contrast thermal switching capabilities with efficient toggling between "on-state" (high thermal conductivity) and "off-state" (low thermal conductivity), which has been extremely difficult to realize in materials.

In the last two decades, there have been several material systems that have demonstrated the thermal switching phenomena triggered by various external stimuli (Fig. 1). These most notably include: changes in molecular orientation in









**Fig. 3** (a) Thermal conductivity as a function of unit cell volume for our flexible COF showing the monotonic decrease of the cross-plane thermal conductivity with increasing volume (or porosity). For the in-plane direction, the thermal conductivity has negligible change as porosity or unit cell volume increases. (b) As the framework expands and the porosity increases, the angle between the polymer chains and the in-plane direction decreases. (c) The cross-plane (z-direction) thermal conductivity increases with contraction since the polymeric chains are better aligned along that direction. (d) In contrast, it decreases for the expanded structure since the polymeric chains are better aligned along the in-plane direction. The increase in porosity with expansion counteracts the influence of chain alignment in the in-plane direction, thus leading to a negligible change in the in-plane thermal conductivity with unit cell volume as shown in (a).

nitride have much higher thermal conductivities (Fig. 4b). This fact, taken together with the results discussed above, suggests that chain alignment is the predominant factor controlling the thermal conductivity for COFs, and as such, can provide guidance for designing COFs with high thermal conductivities for thermal management applications. Moreover, although the densities of the rigid and flexible COFs are comparable to the densities of aerogels, their thermal conductivities, especially for the contracted phase of our flexible COF, are more than an order of magnitude greater (for most cases) than aerogels or other porous materials with similar densities (see Fig. 4b). Therefore, along with the remarkable thermal conductivity switching response for the flexible COFs, our results also mark a new regime of materials design combining ultralow densities with relatively high thermal conductivities, which could be highly beneficial for the design of ultralight-weight structural materials.<sup>49,50</sup>

It is worth noting that the experimentally observed reversible crystal transformation of the flexible COF was through guest adsorption and desorption.<sup>14</sup> In the case of adsorption, the thermal conductivity of the COF might be influenced through scattering of the framework phonons by the guest species, as has been recently shown experimentally for MOFs with various

adsorbed guest molecules.<sup>30,36</sup> Such a guest-induced scattering leads to even lower thermal conductivities as compared to the thermal conductivities calculated for our expanded (empty) frameworks, thus potentially increasing the magnitude of the switching ratio calculated in this work. However, we caution that variations in the guest species and their diffusivities could have varying effects on the overall thermal conductivities of the guest-infiltrated frameworks providing a potentially additional knob to tune their thermal transport properties.<sup>24,25,33</sup> Furthermore, in view of host-guest interactions, recently it has also been shown that the thermal conductivity of organic framework materials can be enhanced significantly *via* increasing the level of interpenetration.<sup>47,48,51,52</sup> For instance, our recent study demonstrated that a 3-fold interpenetration can lead to as much as a 6-fold increase in the room temperature thermal conductivity of COF-300.<sup>47</sup> This enhancement in the heat conduction efficacy was attributed to increased phonon hardening, reduced vibrational scattering at the pores, and lattice stiffening resulting from the supramolecular interactions between the individual frameworks. It should also be noted that along with documentation of several recent advancements in COFs that are responsive to several different external stimuli such as pH levels, metal ions, electricity, light and many others,<sup>53</sup>



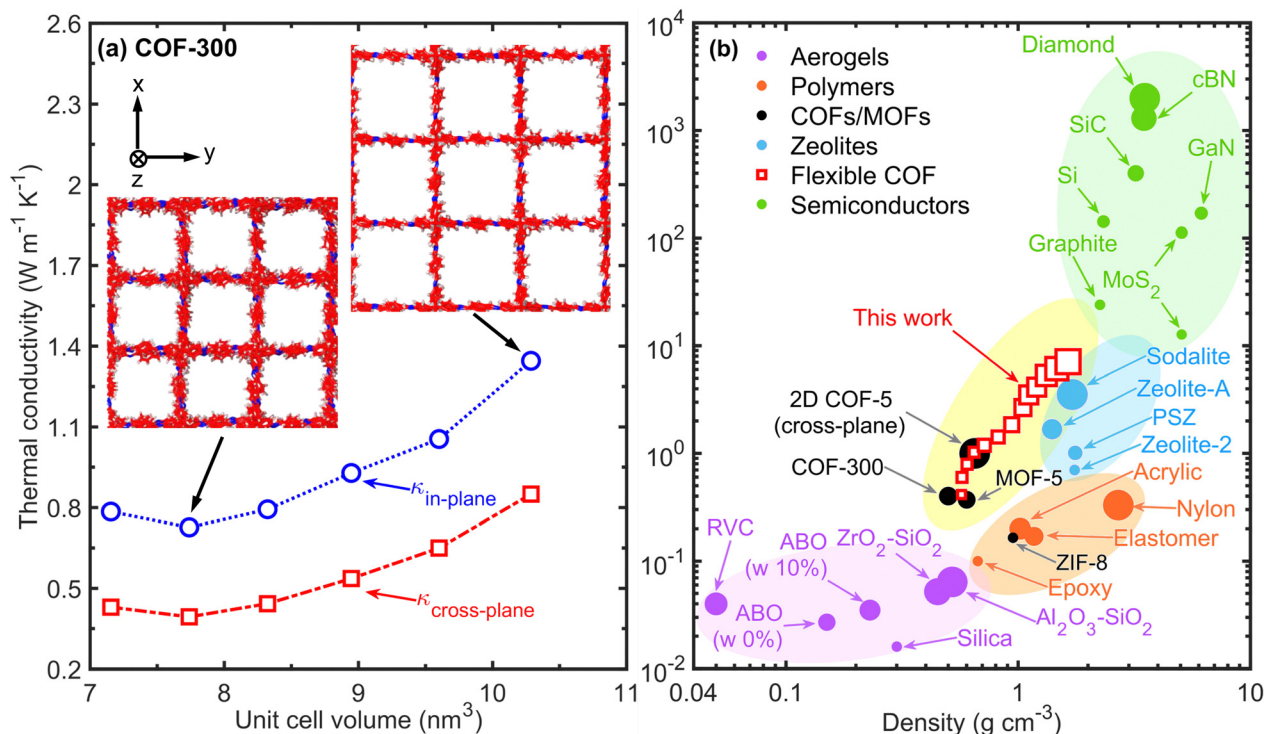


Fig. 4 (a) Thermal conductivity as a function of unit cell volume for our COF-300 framework. In contrast to our flexible COF, expansion of the framework leads to a higher thermal conductivity in COF-300 due to better chain alignment along the principal directions (as shown in the inset). (b) Comparison of thermal conductivity at room temperature as a function of density for our flexible COF with common aerogels, polymers, zeolites, and semiconductors. In general, higher densities are associated with higher thermal conductivities. However, the flexible COFs span a regime of materials design combining low densities with relatively higher thermal conductivity, which has been critically missing. Moreover, our flexible COF also possesses higher thermal conductivities as compared to other framework materials such as COF-300,<sup>47</sup> MOF-5,<sup>28,48</sup> and a recent measurement of cross-plane thermal conductivity of 2D COF-5.<sup>19</sup>

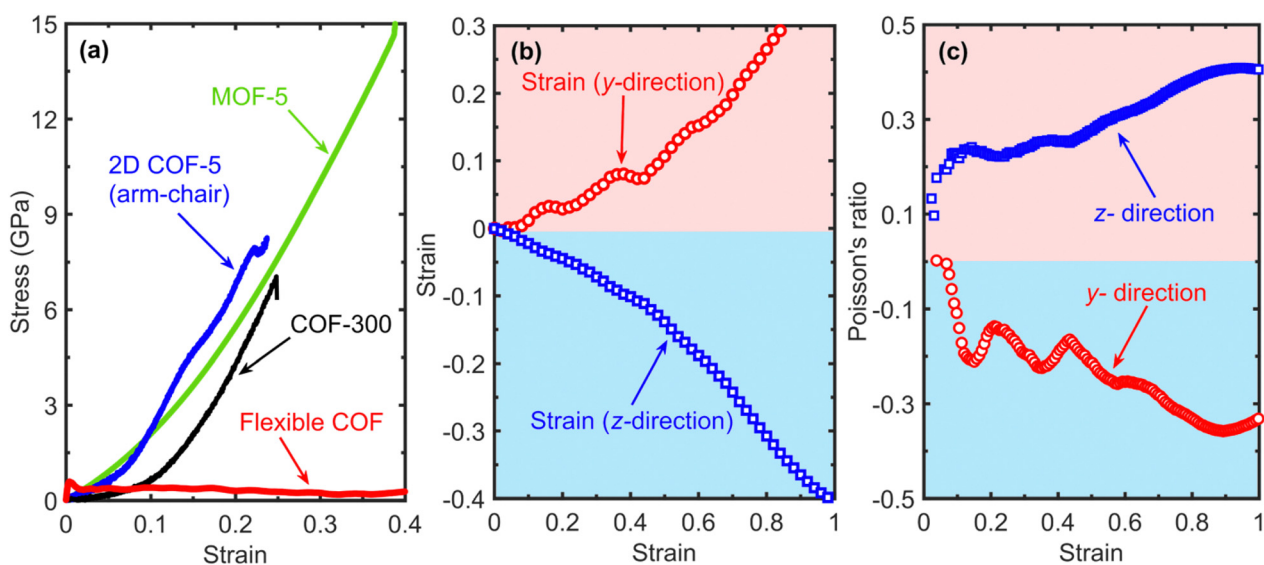


Fig. 5 (a) Comparison of stress versus strain curves calculated from uniaxial tension applied in the x-direction for our flexible COF along with the results for COF-300, MOF-5 and 2D COF-5 (from our prior work).<sup>18</sup> Although the strain causes stress buildup for the other porous frameworks, our flexible COF shows negligible stress even upon strain levels of 80%, which highlights its' highly flexible nature. (b) The resultant strain in the z- and y-directions versus the applied uniaxial strain in the x-direction. While the flexible COF domain contracts in the z-direction, the domain expands considerably in the y-direction. (c) The Poisson's ratio extracted from our uniaxial tensile simulations showing the nonlinear negative values for the y-direction as a function of strain in the x-direction where tension is applied.



the guest-induced structural changes in COFs has most notably been shown to be very swift with response times below 200 ms.<sup>54</sup> Therefore, COFs hold great promise for not only high-contrast but also fast reversible thermal conductivity switching applications.

Finally, we reveal the ultraflexible nature of our dynamic COF by monitoring the stress response to uniaxial tension of the contracted phase along the in-plane direction, as shown in Fig. 5a. For comparison, we also show the stress-strain responses of other similar porous frameworks, namely, COF-300, MOF-5 and 2D COF-5 (taken from our prior work)<sup>18</sup> under uniaxial tension. While there is minimal stress build-up for our dynamic COF, considerable increases in stresses are observed for the rest of the structures. This again highlights the role of the molecular pedal motion of the imine bonds for facile switching between the contracted and expanded phases in response to external stimuli, such as strain in this case. However, guest absorption/desorption can also lead to similar phase changes for 'stress-free' structures.<sup>14</sup>

Our uniaxial tensile simulations on the dynamic COF also reveal a unique physical attribute in these COFs, namely, a negative Poisson's ratio when uniaxial strain is applied along the in-plane direction. As shown in Fig. 5b, while the length of the computational domain shrinks in the cross-plane direction (represented by the negative strain), the computational domain expands along the *y*-direction when uniaxial strain is applied along the *x*-direction. The resulting Poisson's ratios in the cross-plane and the in-plane directions due to uniaxial tensile deformation are shown in Fig. 5c. The mechanism dictating the negative Poisson's ratio along the in-plane direction also derives from the same pedal motion of the imine linkers that facilitates thermal conductivity switching, which is absent in the rigid COF-300 structure for which a positive Poisson's ratio is calculated in all directions (Fig. S9 and S10, ESI†). This auxeticity that we observe for our flexible COF is a unique result since most materials shrink laterally when stretched along the orthogonal direction, characterizing a positive Poisson's ratio with a typical value of 0.33 for most materials.<sup>55</sup>

Materials with a negative Poisson's ratio, although rare, can counterintuitively expand laterally in response to an orthogonal tensile force,<sup>56–62</sup> and are usually accompanied by anomalous or enhanced physical properties,<sup>18,63–68</sup> as with the case of our flexible COF. As such, these materials can not only be transformative for thermally-driven applications, but can also find widespread applications in fields ranging from tissue engineering, and medicine to aerospace and defence.<sup>69–72</sup> In this respect, although auxetic behavior has been previously observed for other materials, such as in some two-dimensional materials,<sup>73–75</sup> honeycomb structures,<sup>65,76</sup> molecular structures,<sup>18,58–60,77,78</sup> and metal organic frameworks,<sup>79,80</sup> the flexible COFs studied in this work combine ultra-flexibility and negative Poisson's ratio with low densities and tunable thermal conductivities, a combination of material properties that highlights a new frontier in the design of multifunctional materials.

In summary, we have demonstrated an unprecedented room-temperature thermal conductivity switching ratio of 18 in a flexible 3D COF capable of reversibly transitioning from an

expanded, low thermal conductivity state, to a contracted, high thermal conductivity state. Our reactive MD simulations have revealed that chain alignment, a critical factor in dictating heat transport in these materials, can be leveraged to modulate the reversible thermal conductivity of the dynamic COF. The key to achieving this dynamic modulation and the high-contrast thermal switching relies on the molecular pedal motion of the imine bonds that respond to exposure from an external stimuli such as mechanical strain or guest adsorption/desorption. Along with their exceptional thermal properties, we have also shown that these COFs are highly flexible and possess negative Poisson's ratio, thus marking a new regime for designing multifunctional materials combining a host of superior physical attributes.

## Conflicts of interest

There are no conflicts to declare.

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